

RELIABILITY REPORT FOR

DS80CH11, Rev A4

Dallas Semiconductor

4401 South Beltwood Parkway Dallas, TX 75244-3292

Prepared by:

Ken Wendel

Ken Wendel Reliability Engineering Manager Dallas Semiconductor 4401 South Beltwood Pkwy. Dallas, TX 75244-3292

Email: ken.wendel@dalsemi.com ph: 972-371-3726

fax: 972-371-6016 mbl: 214-435-6610

Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport /dsreliability.html.

Device Description:

A description of the device used in this qualification can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.

Reliability Derating:

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

```
AfT = exp((Ea/k)*(1/Tu - 1/Ts)) = tu/ts
AfT = Acceleration factor due to Temperature
tu = Time at use temperature (e.g. 55°C)
ts = Time at stress temperature (e.g. 125°C)
k = Boltzmann's Constant (8.617 x 10-5 eV/°K)
Tu = Temperature at Use (°K)
Ts = Temperature at Stress (°K)
Ea = Activation Energy (e.g. 0.7 ev)
```

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

```
AfV = exp(B*(Vs - Vu))

AfV = Acceleration factor due to Voltage

Vs = Stress Voltage (e.g. 7.0 volts)

Vu = Maximum Operating Voltage (e.g. 5.5 volts)

B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)
```

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

```
Fr = X/(ts * AfV * AfT * N * 2)
X = Chi-Sq statistical upper limit
N = Life test sample size
```

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process/assembly is:

FAILURE RATE: MTTF (YRS): 138361 FITS: 0.8

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 B: 0 Tu: 25 °C Vu: 5.5 Volts

The reliability data follows. A the start of this data is the device information. This is a description of the device for this report. Following this is the assembly information. This section includes a description of the assembly vehicle used to generate this reliability data for both qualifications and monitors. The next section is the detailed reliability data for each stress found in the qualification / monitor. If there are additional assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that assembly. The reliability data section includes the latest data available. Some of this data may be generic with other products.

Device Information:

Process: 1P, 2M, 0.6um,SilP1,NdA,PD,Ti/TiN M1+M2,WJ BPSG,N+E

Passivation: Passivation w/Nov TEOS Oxide-Nitride

Die Size: 273 x 340

Number of Transistors: 0

Interconnect: Aluminum / 1% Silicon / 0.5% Copper

Gate Oxide Thickness: 150 Å

Assembly Information:

Qualification Vehicle: DS80CH11
Assembly Site: ATP (Amkor, PI)

Pin Count: 128
Package Type: LQFP
Body Size: 14x20x1.4

Mold Compound: Sumitomo 7320CR Lead Frame: C18045 w/Ag Spot

Lead Finsh: SnPb Plate

Die Attach: M2500 Ag Polymer

Bond Wire / Size: Au / 1.2 mil Flammability: UL 94-V0 Moisture Sensitivity Level 4

(JEDEC J-STD20A)

Date Code Range: 9926 to 0206

ELECTRICAL CHARACTERIZATION

DESCRIPTION	DATE CODE CONDITION		READPOINT		QTY	FAILS	FA#
ESD SENSITIVITY	0206	EOS/ESD S5.1 HBM 500 VOLTS	2	PUL'S	3	0	
ESD SENSITIVITY	0206	EOS/ESD S5.1 HBM 1000 VOLTS	2	PUL'S	3	0	
ESD SENSITIVITY	0206	EOS/ESD S5.1 HBM 2000 VOLTS	2	PUL'S	3	0	
ESD SENSITIVITY	0206	EOS/ESD S5.1 HBM 4000 VOLTS	2	PUL'S	3	3	No FA
ESD SENSITIVITY	0206	EOS/ESD S5.1 HBM 8000 VOLTS	2	PUL'S	3	3	No FA

Total: 6

MOISTURE SENSITIV	ITY LEVE	EL 3					
DESCRIPTION	DATE CODE CONDITION		READPOINT		QTY	FAILS	FA#
PRECONDITION U/S	9926	J-STD-020	2	DYS	8	0	
ULTRASOUND		J-STD-020	2	DYS	8	0	
STORAGE LIFE		125C		HRS	8		
MOISTURE SOAK		30C/60% R.H.	240	HRS	8		
CONVECTION REFLOW		235C +5/-0C	3	PASS	8	0	
EXTERNAL VISUAL		MIL-STD-883-2009	1	DYS Total:	8	0 0	
OPERATING LIFE				Total.			
DESCRIPTION	DATE CO	DDE CONDITION	REAI	DPOINT	QTY	FAILS	FA#
HIGH VOLTAGE LIFE	0206	125C, 6.0 VOLTS	1000	HRS	80	0	
HIGH VOLTAGE LIFE	0206	125C, 6.0 VOLTS	1000	HRS	80	0	
HIGH VOLTAGE LIFE	0206	125C, 6.0 VOLTS	1000	HRS	80	0	
INFANT LIFE	9926	125C, 6.0 VOLTS	48	HRS	340	0	
HIGH VOLTAGE LIFE	9926	125C, 6.0 VOLTS	1000	HRS	170	0	
				Total:		0	
PACKAGE TESTS							
DESCRIPTION	DATE CO	DDE CONDITION	REA	DPOINT	QTY	FAILS	FA#
SOLDERABILITY	9926	MIL-STD-883-2003	1	DYS	3	0	
X-RAY	9926	MIL-STD-883-2012 : TOP & SIDE VIEW	2	DYS	6	0	
PHYSICAL DIMENSIONS		MIL-STD-883-2016	4	DYS	6	0	
MARK PERMANENCY		MIL-STD-883-2015	6	DYS	6	0	
LEAD INTEGRITY		MIL-STD-883-2004 : COND B2	8	DYS	6	0	
				Total:		0	
TEMPERATURE CYCI	LE						
DESCRIPTION		DDE CONDITION		DPOINT	QTY	FAILS	FA#
TEMP CYCLE	9926	-55C TO 125C	1000	CYS	77	0	
				Total:		0	
TEMPERATURE HUM	IDITY BIA	AS					
DESCRIPTION	DATE CO	ODE CONDITION	REA	DPOINT	QTY	FAILS	FA#
BIASED MOISTURE	9926	85/85, 5.5 VOLTS	949	HRS	48	1	No FA
				Total:		1	
UNBIASED MOISTURI	E RESIST	TANCE					
DESCRIPTION	DATE CO	ODE CONDITION	REA	DPOINT	QTY	FAILS	FA#
HAST, NO BIAS	9926	130C, 85% R.H.		HRS	45	0	
				Total:		0	

Assembly Information:

Qualification Vehicle: DS80CH11 Assembly Site: ATK (Amkor, K)

Pin Count: 128
Package Type: LQFP
Body Size: 14x20x1.4

Mold Compound: Sumitomo 7320CR Lead Frame: EFTEC 64T w/Ag Spot

Lead Finsh: SnPb Plate

Die Attach: M2500 Ag Polymer

Bond Wire / Size: Au / 1.2 mil Flammability: UL 94-V0 Moisture Sensitivity Level 4

(JEDEC J-STD20A)

Date Code Range: 9908 to 0113

OPERATING LIFE							
DESCRIPTION	DATE CODE CONDITION READPOINT		QTY	FAILS	FA#		
HIGH VOLTAGE LIFE	0018	125C, 6.0 VOLTS	1000	HRS	116	0	
INFANT LIFE	0033	125C, 6.0 VOLTS	48	HRS	235	0	
HIGH VOLTAGE LIFE	0033	125C, 6.0 VOLTS	1000	HRS	77	0	
HIGH VOLTAGE LIFE	0103	125C, 6.0 VOLTS	1000	HRS	77	0	
INFANT LIFE	0103	125C, 6.0 VOLTS	48	HRS	235	0	
HIGH VOLTAGE LIFE	0113	125C, 6.0 VOLTS	1000	HRS	80	0	
INFANT LIFE	9908	125C, 6.0 VOLTS	48	HRS	263	0	
HIGH VOLTAGE LIFE	9908	125C, 6.0 VOLTS	1000	HRS	170	0	
HIGH VOLTAGE LIFE	9949	125C, 6.0 VOLTS	1000	HRS	116	0	
				Total:		0	
PRECONDITIONING L	EVEL 3						
DESCRIPTION	DATE COD	E CONDITION	READPOINT		QTY	FAILS	FA#
ULTRASOUND	0033	J-STD-020	1	DYS	4	0	
STORAGE LIFE	0033	125C	24	HRS	239		
MOISTURE SOAK CONVECTION REFLOW		30C/60% R.H. 235C +5/-0C	240 3	HRS PASS	239 239	0	
	0000						
PRECONDITION U/S	0033	J-STD-020	1	DYS	4	0	
ULTRASOUND	0103	J-STD-020	1	DYS	4	0	
STORAGE LIFE	0103	125C	24	HRS	239		
MOISTURE SOAK CONVECTION REFLOW		30C/60% R.H. 235C +5/-0C	240 3	HRS PASS	239 239		
	0.4.00						
PRECONDITION U/S	0103	J-STD-020	1	DYS	4	0	
ULTRASOUND	0113	J-STD-020	1	DYS	4	0	
STORAGE LIFE	0113	125C	24	HRS	244		
MOISTURE SOAK		30C/60% R.H.	192	HRS	244		NONE
CONVECTION REFLOW		235C +5/-0C	3	PASS	244	1	NONE
PRECONDITION U/S	0113	J-STD-020	1	DYS	4	0	

				Total:		1	
TEMPERATURE CYC	LE						
DESCRIPTION	DATE C	CODE CONDITION	REA	ADPOINT	QTY	FAILS	FA#
TEMP CYCLE	0033	-55C TO 125C	100	0 CYS	70	0	
TEMP CYCLE	0103	-55C TO 125C	100	0 CYS	70	0	
TEMP CYCLE	0113	-55C TO 125C	100	0 CYS	70	0	
TEMP CYCLE	9908	-55C TO 125C	100	0 CYS	77	0	
				Total:		0	
TEMPERATURE HUM	IIDITY B	AS					
DESCRIPTION	DATE C	CODE CONDITION	REA	ADPOINT	QTY	FAILS	FA#
BIASED MOISTURE	0033	85/85, 5.5 VOLTS	959	HRS	32	0	
BIASED MOISTURE	0103	85/85, 5.5 VOLTS	959	HRS	48	0	
BIASED MOISTURE	0113	85/85, 5.5 VOLTS	959	HRS	31	0	
				Total:		0	
UNBIASED MOISTUR	E RESIS	STANCE					
DESCRIPTION	DATE C	DATE CODE CONDITION		ADPOINT	QTY	FAILS	FA#
HAST, NO BIAS	0033	130C, 85% R.H.	100	HRS	39	0	
HAST, NO BIAS	0103	130C, 85% R.H.	100	HRS	40	0	
HAST, NO BIAS	0113	130C, 85% R.H.	100	HRS	44	0	
				Total:		0	
Assembly Informat	ion:						
Qualification Vehi Assembly Site: Pin Count: Package Type: Body Size: Mold Compound: Lead Frame: Lead Finsh: Die Attach:		DS80CH11 Stats 128 LQFP 14x20x1.4 Sumitomo 7320CR Stamped Copper C7025 SnPb Plate 84-1 LMISR4 Epoxy Silverfilled	Ablebond				
Bond Wire / Size:		Au / 1.2 mil	,				
Elammahility:		LIL 04 VO					

UL 94-V0

Flammability: Moisture Sensitivity (JEDEC J-STD20A) Level 4

Date Code Range: 0110 to 0110

ΩI	ΡF	RΔ	Т	NG	IFE
v	_			170	

DESCRIPTION	DATE CODE CONDITION		RI	EADPOINT	QTY	QTY FAILS	
HIGH VOLTAGE LIFE	0110	125C, 6.0 VOLTS	10	000 HRS	80	0	
				Total:		0	

PRECONDITIONING	LEVEL 3

DESCRIPTION	DATE CODE CONDITION		READPOINT		QTY FAILS		FA#
ULTRASOUND	0110	J-STD-020	1	DYS	4	0	
STORAGE LIFE	0110	125C	24	HRS	242		

MOISTURE SOAK	0110	60C/60% R.H.		40	HRS	242		
CONVECTION REFLOW	1	235C +5/-0C		3	PASS	242	0	
PRECONDITION U/S	0110	J-STD-020		1	DYS	4	0	
					Total:		0	
TEMPERATURE CYC	LE							
DESCRIPTION	DATE CODE CONDITION			READPOINT		QTY	FAILS	FA#
TEMP CYCLE	0110	-55C TO 125C		1000	CYS	70	0	
					Total:		0	
TEMPERATURE HUN	IIDITY BIA	ıs						
DESCRIPTION	DATE CO	DATE CODE CONDITION		READPOINT		QTY	FAILS	FA#
BIASED MOISTURE	0110	85/85, 5.5 VOLTS		959	HRS	42	0	
					Total:		0	
UNBIASED MOISTUR	RE RESIST	ANCE						
DESCRIPTION	DATE CO	DDE CONDITION		REA	DPOINT	QTY	FAILS	FA#
HAST, NO BIAS	0110	130C, 85% R.H.		100	HRS	40	0	
					Total:		0	
FAILURE RATE:	N	MTTF (YRS): 138361	FITS:	8.0				